

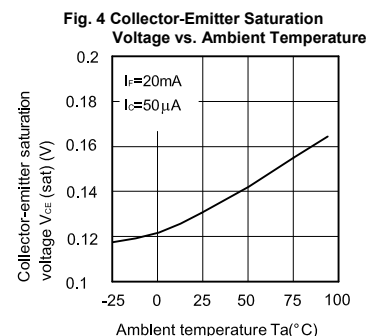
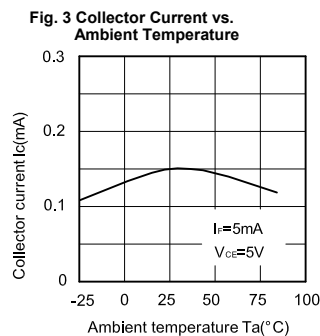
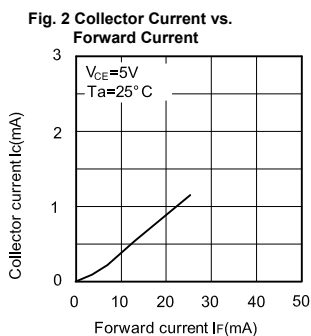
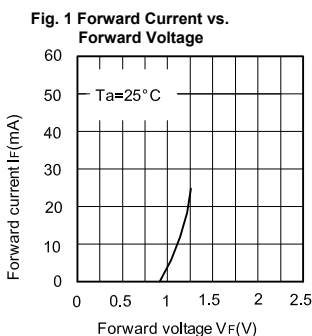


### ABSOLUTE MAXIMUM RATINGS at $T_A=25^\circ\text{C}$

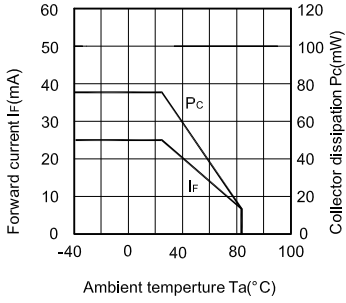
Parameter		Symbol	Rating	Unit
Input	Forward current <sup>[1]</sup>	$I_F$	25	mA
	Reverse voltage	$V_R$	5	V
	Power dissipation	$P_D$	35	mW
	Peak Forward Current (Pulse Width $\leq 100\mu\text{s}$ , Duty Cycle=1%)	$I_{FP}$	1	A
Output	Collector-emitter voltage	$V_{CEO}$	20	V
	Emitter-collector voltage	$V_{ECO}$	5	V
	Collector current	$I_C$	20	mA
	Collector power dissipation	$P_C$	75	mW
Operating temperature		$T_{opr}$	-40~+85	$^\circ\text{C}$
Storage temperature		$T_{stg}$	-40~+90	$^\circ\text{C}$
Manual soldering <sup>[2]</sup>		$T_{sol}$	300	$^\circ\text{C}$

Notes:  
 1. Refer to the temperature rating chart if the ambient temperature exceeds  $25^\circ\text{C}$ .  
 2. Complete soldering within 3 seconds.  
 3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

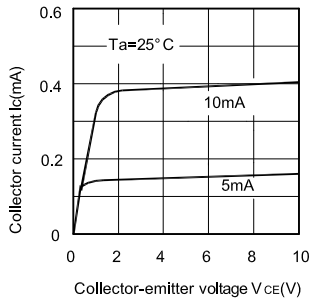
### TECHNICAL DATA



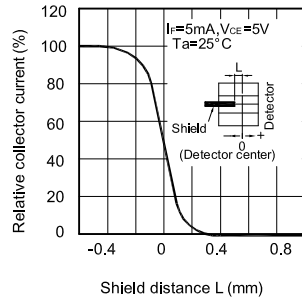
**Fig. 5 Forward Current vs. Collector Dissipation Temperature Rating**



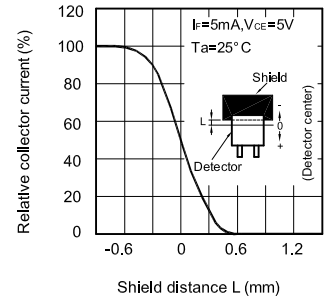
**Fig. 6 Collector Current vs. Collector-Emitter Voltage**



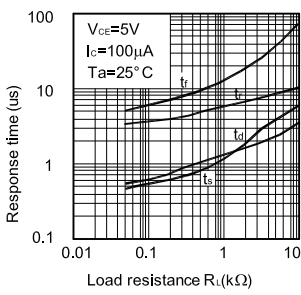
**Fig. 7 Relative Collector Current vs. Shield Distance(1)**



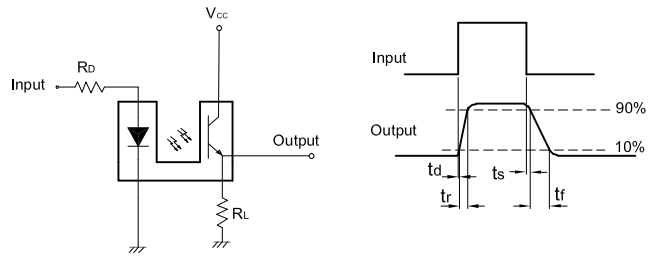
**Fig. 8 Relative Collector Current vs. Shield Distance(2)**



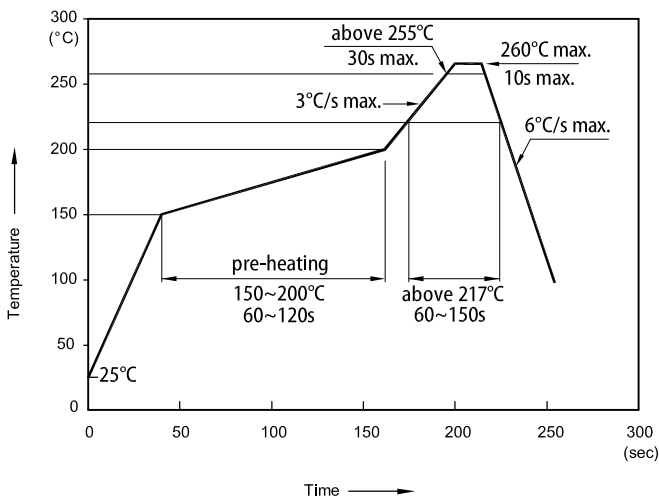
**Fig. 9 Response Time vs. Load Resistance**



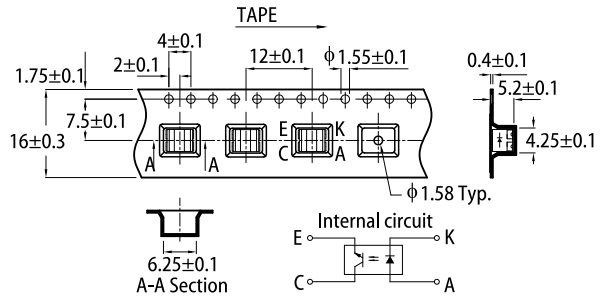
**Test Circuit for Response Time**



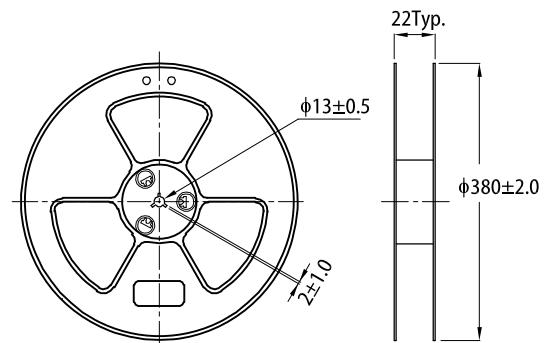
**REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS**



**TAPE SPECIFICATIONS (units : mm)**



**REEL DIMENSION (units : mm)**



- Notes:
1. Don't cause stress to the LEDs while it is exposed to high temperature.
  2. The maximum number of reflow soldering passes is 2 times.
  3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

## PACKING & LABEL SPECIFICATIONS

